

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

RICHARD W. ARNOLD ET AL.

Serial No. 09/164,580 (TI-22561)

Filed October 1, 1998

For: KNOWN GOOD DIE USING EXISTING PROCESS INFRASTRUCTURE

Art Unit 2822

Examiner J. Mitchell

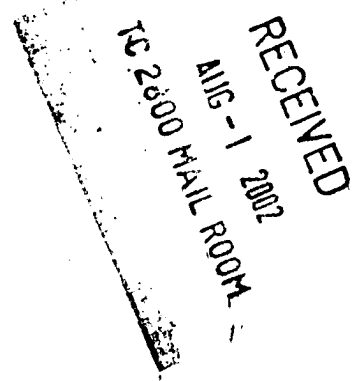
Commissioner for Patents
Washington, D. C. 20231

Sir:

PETITION TO COMMISSIONER

Applicants, through their attorney, hereby petition the Commissioner of Patents and Trademarks to enter the amendment filed after final rejection for the reasons stated hereinbelow. No charge is believed to be necessary since the error is that of the examiner. However, should a charge be required, please charge any costs to Deposit Account No. 20-0668.

The facts are that claim 30 was copied from Potter Patent No. 6,028,437 and contained an indefinite antecedent which was noted by the examiner in the alleged final rejection and corrected in an amendment filed after final rejection. This was **the only** amendment requested in the amendment filed after the alleged final rejection. A copy of



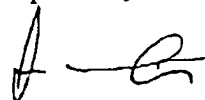
the claim as set forth in the amendment filed after final rejection is reproduced as follows:

30. (Amended) An apparatus adaptable for the testing of semiconductor devices comprising:
a package, wherein said package has a package lid having a lower surface adapted for receiving said semiconductor device, said semiconductor device having an upper surface, and a package base having an upper surface;
an interconnecting medium contained within said package, wherein said [probe membrane] interconnecting medium has electrical paths adaptable for coupling to test circuitry, said medium including a medium surface, said medium surface having a plurality of probe tips affixed thereto, a plurality of standoffs affixed thereto, and a lower surface, wherein said probe tips are adaptable for making electrical contact with pads on said semiconductor device and are compliant bump probe tips;
a bonding layer comprising an elastomeric material interposed between said package lid lower surface and said semiconductor device upper surface; and
a bond layer comprising an elastomeric material interposed between said interconnecting medium lower surface and said package base upper surface, said package base being adapted for receiving said interconnecting medium.

The amendment was refused entry on the ground that it raised the issue of new matter. Clearly, there can be no issue of new matter when the only change was that of correcting an indefinite antecedent as noted by the examiner himself.

In view of the above, entry of the amendment filed after final rejection is requested.

Respectfully submitted,



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